



MU DMPU FB TMIREC LB JC I EC ASPOLR

MU GBSAR LACN AI EC

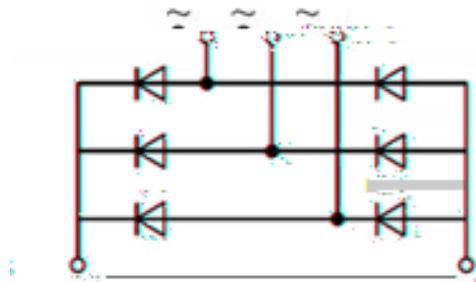
GF QSPEC ASPOLRA N @GB

4 00+		4
"		
1+ R KQ		
4 + V		4

GB QSNU DMP" ! KMRMQ

GC PCARFGQDMP LQGMFGOB ! KMRMPAVLFRMUCPQ

, ML AMLRMJ @C PCARFGQDMP ! " ! AMLTCPQ



2₁ ! SLJQQMFCPU GC QNCAGGB

0 CNOBFC NC I FCTOPC TMIREC		4 00+		4
, ML FONOFC NC I FCTOPC TMIREC		4 01+		4
- SNSRASPOLR	2 ₁ °C	"		
MRU FB QSPEC ASPOLR	A AC 1 GCU TC 2 _{TH} °C	1+		
RT JC DMPDQGE		R		Q
0+1 GMJ RML TMIREC	! Q K G	4 1-		4
(SLARML RCK NCP RSPC P LEC		2(		
1 RMP ECRK NCP RSPC P LEC		2 QE		°C



2, ! SLJQQMFOPU GC QNCAGB

MRU FB TMREC	" 2TH °C	4				4
0 CTOPC JC I EC ASFCLR	40 400+ 2TH °C	00+				K
	40 400+ 2TH °C					K
2FROQMB TMREC	MPNMUCP MQA ASJ RML MJ 2TH °C	42-				4
" L K APOGR LAC		P2				K

2, ! SLJQQMFOPU GC QNCAGB

2FORK JG NOB LAC HSLARML RMA GC	NCPBQBC	0FHA				) 5
+ MSLRGE RMOSC	QC NJ RCRMFC RQGI QAPU +	+				, K
	JCARMBCRMORP G J QAPU +					, K

(+ " 2" "	(+ " 2" "	"	E. ! 1	. ! 1	. ! 1

FIG.1: Forward characteristics(per diode)

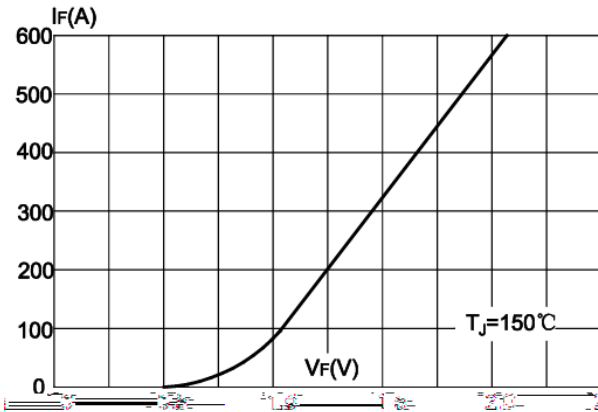


FIG.2: Peak on-state surge current

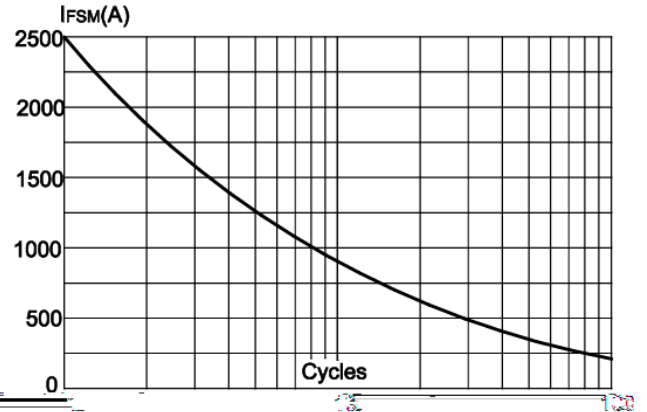


FIG 3: Forward current vs. case temperature

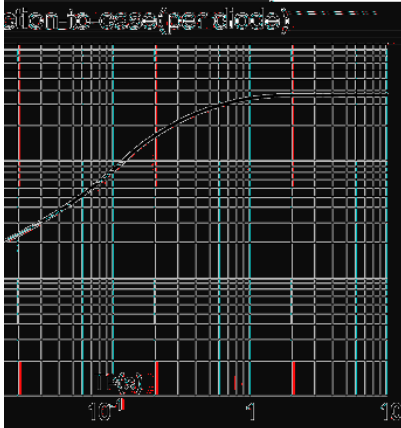
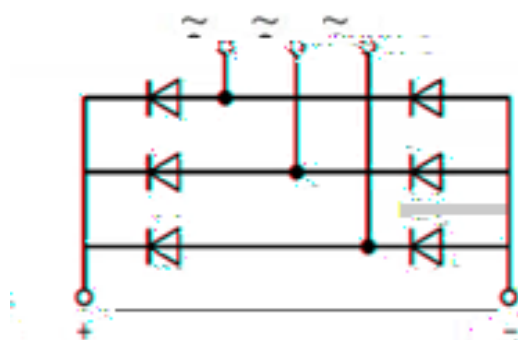
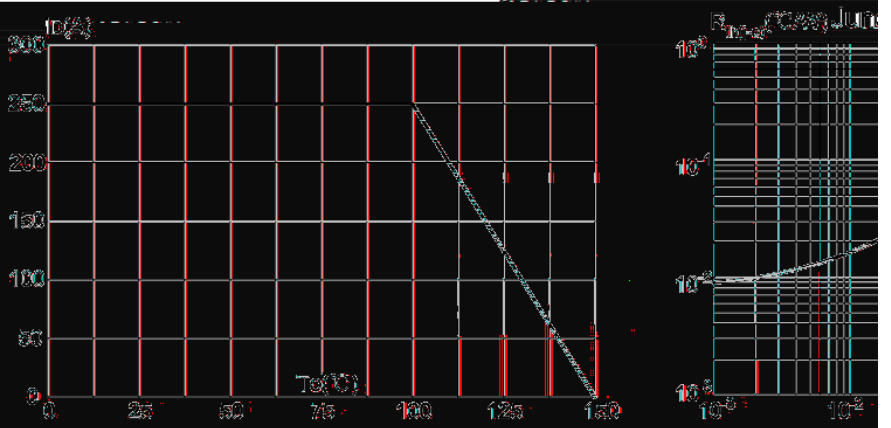
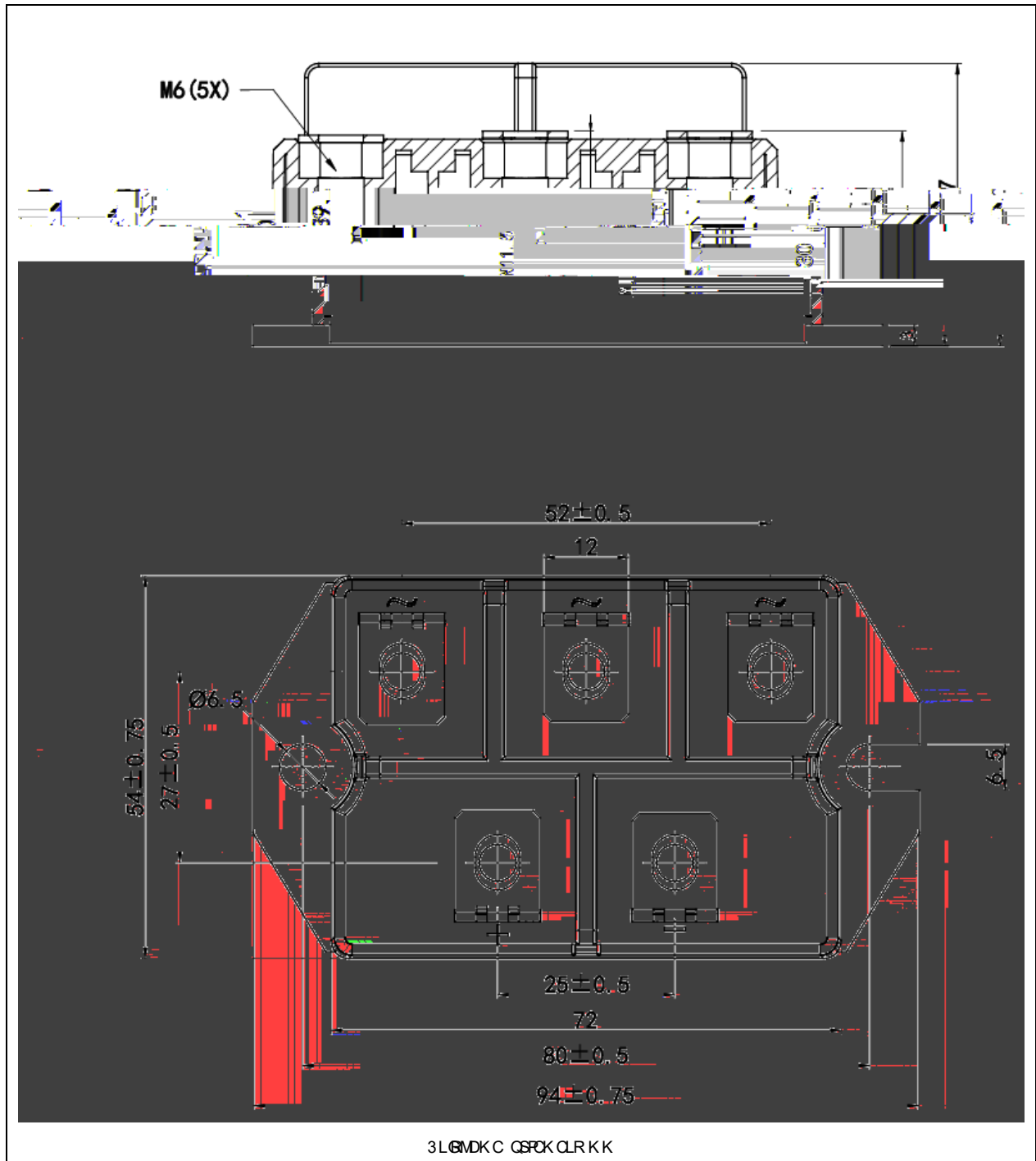


FIG 4: Maximum transient thermal impedance







LDPK ROL DPLGFOB G FEG BMASK CLRQ @JGTB RM @ AASP RC LB PCG@C MUCTOP
(GLEQS(G(G1CK @MLBSAMP! M FB QOSK QQLMPCQMLQ@B DMPFC AMLOOSCLACQMSQC
UGMSRAVLQBOP ROL DMPQSAF GDMK ROL LMPSCC @ MLB G 2FG GDMK ROL G FEG BMASK CLR
GQS@CARMAF LECUGMSRNPLMPC, MRUGORLBGE FEG (GLEQS(G(GUGISJ AVKNJ
UG FFC RPK QMSRGOB G QELOB EPOCK CLR . RVBSAQ LB GDMK ROL NMTBOB G FEG
BMASK CLRF TC LM GDPECK CLRMDN RLRQ (GLEQS(G(G QOSK QQLMPCQMLQ@B DMP L
GDPECK CLRMDMFCOPFFQMDRFB N FGQUF@F K PQSJDMK FFC SQC MDQSAF NVBSAQ LB
GDMK ROL 2FG BMASK CLRQ FFC GEGJ PC C B RB (SJ 2FG BMASK CLR
QSNCPQBOQ LB PCNU ACQ JGDMK ROL NPCT@SQ QSNUGB

 Q FEG FFCB FP BOK P MD(GLEQS(G(G1CK @MLBSAMP! M R (GLEQS(G(G
1CK @MLBSAMP! M FB JFEGFQPCQPTOB